

Sheet 1 of 1
EV372467541

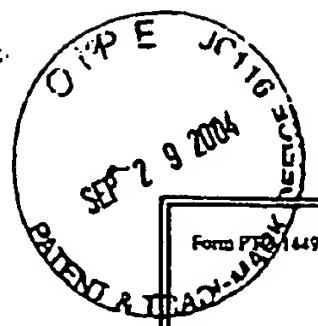
Form PTO-145 (May 2002)				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M140-273		SERIAL NO. 09/502,693	
LIST OF ART CITED BY APPLICANT <small>(Use several sheets if necessary)</small>				APPLICANT Micron Technology, Inc.		FILING DATE February 11, 2000		GROUP 3684	
U.S. PATENT DOCUMENTS									
*Examiner Initial	Document Number	Date	Name			Class	Subclass	Filing Date If Appropriate	
AA								RECEIVED	
AB								OCT 08 2004	
AC								Technology Center 260	
AD									
AE									
AF									
AG									
AH									
AI									
AJ									
AK									
FOREIGN PATENT DOCUMENTS									
Document Number	Date	Country			Class	Subclass	Translation		
AL	0 172 445 A1	07/1985	EPO (Statement of Relevance provided in IDS)			<input checked="" type="checkbox"/>	<input type="checkbox"/>		
AM	0 682 382 A2	04/1995	EPO (Statement of Relevance provided in IDS)			<input checked="" type="checkbox"/>	<input type="checkbox"/>		
AN	0 682 382 A3	05/1995	EPO (Statement of Relevance provided in IDS)			<input checked="" type="checkbox"/>	<input type="checkbox"/>		
AO									
AP									
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
AR									
AS									
AT									
EXAMINER					DATE CONSIDERED				
<small>*EXAMINER: Initial if reference considered. Whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>									



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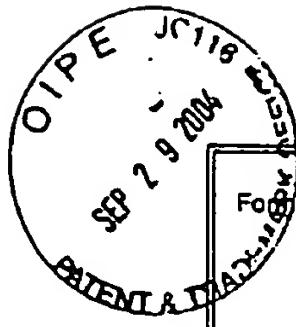
Form 160-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M140-373	SERIAL NO. 09/502,643		
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT Micron Technology, Inc.			
				FILING DATE February 11, 2000	GROUP 3662		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,361,403	11/1994	Dew	455	74	
	AB	5,423,074	06/1995	Dew	455	74	
	AC	5,283,646	11/1988	Masuzaki	340	572	
	AD	5,072,194	12/1991	Chevalier	330	260	
	AE	5,300,596	04/1994	Soczman	330	260	RECEIVED
	AF	5,365,192	11/1994	Wagner et al.	330	252	OCT 08 2000
	AG	5,394,159	03/1995	Schneider et al.	343	70	Technology Center 2600
	AH	4,190,838	02/1980	Kemp	343	15	
	AI	5,311,090	04/1996	Demba et al.	375	205	
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
	AL	0 172 445 A1	07/1985	EPO			Yes
	AM	0 682 382 A2	04/1995	EPO			1
	AN	0 682 382 A3	05/1995	EPO			1
	AO	DE 3212876 A1	04/1983	Germany			1
	AP	0 616 429 A1	01/1991	EPO			1
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	N.J. Woods et al. "One micrometre scale self-aligned cobalt disilicide Schotky barrier diodes". ELECTRONICS LETTERS, IEE Stevenage, GB.					
		Vol. 31, No. 20, Oct. 1995, pages 1878-1880					
	AS	Shenai Krishna. "Characteristics of LPCVD WS2/N-Si Schotky Contacts". IEEE ELECTRON DEVICE LETTERS, U.S. IEEE INC. N.Y., Vol. 12					
		No. 4, April 1991, pages 169-171					
	AT						
EXAMINER				DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p> <p style="text-align: center;">Copy</p>							



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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE					ATTY. DOCKET NO. M140-273	SERIAL NO. 09/502,693	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT Micro Technology, Inc.		
					FILING DATE February 11, 2000	GROUP 2687	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
~	AA	5,640,151	06/17/97	Rcis et al.	340	823,54	
~	AB	4,384,288	05/17/83	Walton	340	823,34	
~	AC	4,514,731	04/30/85	Falk et al.	340	823,08	
~	AD	4,868,908	09/19/89	Pless et al.	323	267	
~	AE	5,103,156	04/07/92	Jones et al.	320	33	
~	AF	5,406,297	04/16/95	Caswell et al.	343	741	
~	AG	5,485,520	01/16/96	Cham et al.	380	24	
	AH						OCT 08 2004
	AI						Technology Center 2600
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Transliteration
	AL						Yes No
	AM						
	AN						
	AO						
	AP						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR						
	AS						
	AT						
EXAMINER <i>Phil J. H. S.</i>				DATE CONSIDERED 2/2/2005			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							



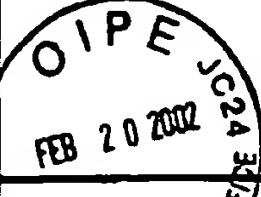
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Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI40-273	SERIAL NO. 09/502,693		
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		RECEIVED			
				FILING DATE February 11, 2000	OCT 08 2004 3882 2684 Technology Center 2000		
U.S. PATENT DOCUMENTS							
Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Applicable
<i>a</i>	<i>AA</i>	4,843,354	06/1989	Fuller et al.	333	81	
<i>w</i>	<i>AB</i>	5,448,770	09/1995	Hietala et al.	455	125	
<i>w</i>	<i>AC</i>	5,696,025	12/1997	Violette et al.	437	175	
<i>w</i>	<i>AD</i>	5,741,462	04/1998	Nova et al.	422	68.1	
<i>w</i>	<i>AE</i>	3,694,776	09/1972	Linder	333	17	
<i>w</i>	<i>AF</i>	3,921,094	11/1975	Schaible	331	1	
<i>w</i>	<i>AG</i>	5,121,407	06/1992	Partyka et al.	375	1	
<i>w</i>	<i>AH</i>	5,334,951	08/1994	Hogeboom	331	1	
<i>w</i>	<i>AI</i>	5,705,947	01/1998	Jeong	327	270	
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
	<i>AJ</i>						Yes
	<i>AK</i>						No
	<i>AL</i>						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
<i>AM</i>							
<i>AN</i>							
<i>AO</i>							
EXAMINER <i>Fuller</i>	DATE CONSIDERED <i>2/2/2005</i>						
'EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.'							

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Form PTO-149  U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE LIST OF ART CITED BY APPLICANT <small>(Use several sheets if necessary)</small>				ATTY. DOCKET NO. MI40-273	SERIAL NO. 09/502,693		
				APPLICANT Micro Technology, Inc.			
				FILING DATE February 11, 2000	GROUP 2687		
U.S. PATENT DOCUMENTS							
*Examiner Initials	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
~	AA 5,361,403	11/1994	Dent	455	74		
~	AB 5,423,074	06/1995	Dent	455	74		
~	AC 4,783,646	11/1988	Matsuaki	340	572		
~	AD 5,072,194	12/1991	Chevallier	330	260		
~	AE 5,300,896	04/1994	Suesserman	330	260		
~	AF 5,365,192	11/1994	Wagner et al.	330	252		
~	AG 5,394,159	02/1995	Schneider et al.	343	700		
~	AH 4,190,838	02/1980	Kemp	343	18		
~	AI 5,511,090	04/1996	Denton et al.	375	205		
~	AJ						
~	AK						
FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
~	AL 0 172 445 A1	07/1985	EPO	RECEIVED		Yes	No
~	AM 0 682 382 A2	04/1995	EPO			x	
~	AN 0 682 382 A3	05/1995	EPO	MAR 11 2002		x	
~	AO D5-3212876 A1	04/1985	Germany	Technology Center 2600		x	
~	AP 0 616 429 A1	01/1994	EPO			x	
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
~	AR	N.J. Woods et al., "One micrometre scale step-aligned cobalt disilicide Schottky barrier diodes", ELECTRONICS LETTERS, IEE Stevenage, GB,					
		Vol. 31, No. 21, Oct. 1995, pages 1878-1880					
~	AS	Shenai Krishna, "Characteristics of LPCVD WS12/N-Si Schottky Contacts", IEEE ELECTRON DEVICE LETTERS, US, IEEE INC. N.Y., Vol. 12					
		No. 4, April 1991, pages 169-171					
~	AT	GROUP 3600					
EXAMINER	P. S. Sathya		DATE CONSIDERED		6/18/07		
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